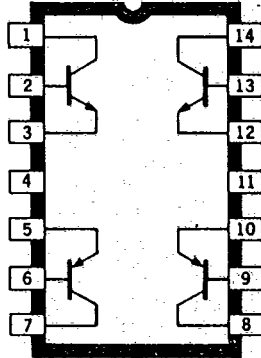


CHIPS-IN-DIPS

T-42-90

CUSTOM-ARRAY PROGRAM



Dwg. No. A-10,053A

MAXIMUM RATINGS

Package Power Dissipation, P_D 2 W*
 Operating Temperature Range,
 T_A -55°C to +150°C
 Storage Temperature Range,
 T_S -65°C to +150°C

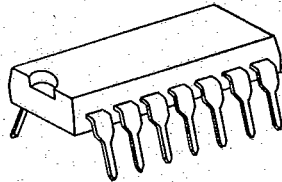
* Derate at the rate of 16 mW/°C above $T_A = +25^\circ\text{C}$

The Chips-In-DIPs program uses discrete semiconductor chips from a comprehensive line of standard devices to create transistor, diode, and Darlington arrays assembled to users' specifications.

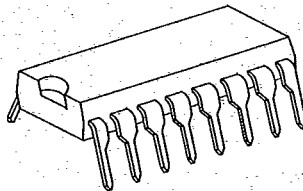
The program provides extensive special-design capabilities for applications with design restrictions such as short lead time, small quantities, and unique circuit requirements. Chips-In-DIPs is an attractive alternative to development of monolithic integrated circuits and commitment to high-volume purchases.

Assembly of discrete devices in dual in-line packages allows relatively higher power dissipation while reducing handling and boosting component density. The standard molded DIP, the package most commonly used for automated circuit assembly, offers superior mechanical protection of components during automatic insertion into printed wiring boards.

Series TPQ transistor arrays, Series TND diode arrays, and Series TPP Darlington arrays are among standard products offered by the Chips-In-DIPs program. Semiconductor chips available for custom-array products include those described in the most recent issue of Brochure CN-193.



Dwg. No. A-11,562A



Dwg. No. A-11,420A